IPC ASSOCIATION ELECTRONIC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and M	ials and Mfg Information			
Supplier	Information														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi											2024-04-20				
Contact N	ame		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
Product-H	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item		Number Mfr Item Name				Effective Date Version Manufacturing Si		Manufacturing Site		Weight*	UOM	Unit Type		
		NIS5021MT1TXG 12V e		12V eFuse		2024-04-20		1	MY1		41.175	mg	Each		
Janufa	cturing Proccess Informa	ation						•					·		
	Terminal Plating / Grid Array Material Termina			rminal Base Alloy J-STD-020 MSL Ratin			Peak Process Body Temperature Max Time at Peak				Tempera	ture Num	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy 1					260		C	30	secon	nds 3					
Comments															
evel 1 - m	aximum time at peak temperat	ture during sol	dering is 10-3	0 seconds											
or more	information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shall apply the interest of the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.41	mg	Supplier	Silicon (Si)	7440-21-3		1.41	mg
Die Attach Epoxy	0.11	mg		Epoxy resin	proprietary data		0.0715	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0385	mg
Lead Frame	20.675		Supplier	Silver (Ag)	7440-22-4		0.3539	mg
			Supplier	Tin (Sn)	7440-31-5		1.2388	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0389	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0584	mg
			Supplier	Copper (Cu)	7440-50-8		18.9362	mg
Mold Compound-Black	17.64		Supplier	Silica Amorphous (SiO2)	7631-86-9		1.323	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0882	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		14.0238	mg
			Supplier	EpoxyNovolaCresins (Cresolic)	64425-89-4		0.882	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.323	mg
Wire Bond - Au	1.34	mg	Supplier	Gold (Au)	7440-57-5		1.34	mg